

# **Board Level Cooling – Surface Mount 5734**



## **BOARD LEVEL COOLING - Surface Mount 5734**

Surface Mount 5734 is a series of surface mount board level heat sinks designed to cool Dual Flat No-Leads (DFN) packages, Quad Flat No-Leads (QFN) packages, D3 Pak, and TO-268 devices. Surface Mount 5734 can cool either a single D3 Pak, larger QFNs or DFNs, or multiple QFNs or DFNs. The tin plated surface of Surface Mount 5734 enables direct soldering to Printed Circuit Boards (PCBs) for effective board cooling.

573400D00000G is the bulk packaging option of Surface Mount 5734 and 573400D00010G is the tape and reel offering for high volume manufacturing. Representative image only.

#### ORDERING INFORMATION

Part Number	Device Type
573400D00000G	QFN, DFN, D3 Pak,TO-268
573400D00010G	D3 Pak/TO-268

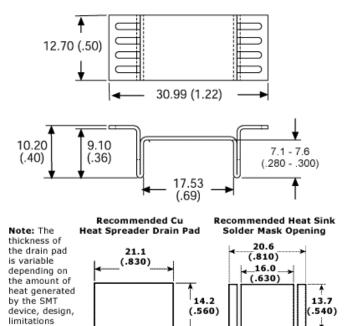
### **HEAT SINK DETAILS**

Property	Details
Material	Copper
Finish	Tin Plated
<b>Device Attachment Options</b>	-
Thermal Interface Material	-

Property	Details
Heat Sink Width (mm)	30.99
Heat Sink Length (mm)	12.70
Heat Sink Height (mm)	10.20
Heat Sink Mounting Direction	Horizontal

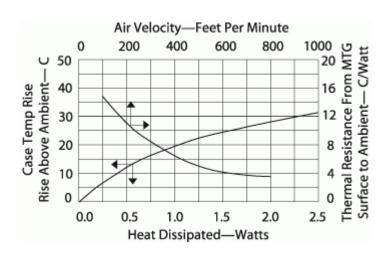
# **MECHANICAL & PERFORMANCE**

Drawing dimensions are shown in mm, (in)



0.8

(.030)



USA: 1.855.322.2843 EUROPE: 39.051.764002 ASIA: 86.21.6115.2000 x8122

and process. This is the

printed circuit.

exposed



1.4

(.060)